

AUTO MOLD



COMPRESSION AUTO MOLD S - 1000



High Productivity

- 2 Strips (Max. 100 x 300) / Press



Precise Control

- Powder Weight Control : $\pm 0.1g$
- Laser Scanning (Die Existence Detection, for Weight Compensation)



Unique Power Supplying Design

- Minimized Film Usage
- Minimized Compound Usage



Package Quality Inspection (Optional)

- Quality Vision Inspection (Optional)
- Capability to Integrate with Other Process (In-line System)



Semiconductor

AUTO MOLD

Enhanced Machine Features

■ Cost Saving Design

- Minimized Film Usage
- Minimized Compound Usage

■ Advanced Features

- Various Clamping Tonnage (120 Ton, 175 Ton)
- Field Proven Excellent Molding Quality
- Modular Concept (Max. 4 Modules)
- Optional Quality Vision Inspection



COMPRESSION AUTO MOLD S - 1000



AUTO MOLD S - 1500

Application	Lead Frame	mm	20~100 (W) x 100~300 (L)			
	Magazine	mm	Max. 105x305x170 (Input Slotted, WxLxH)		Max. 105x305x170 (Input Slotted, WxLxH)	
			Max. 105x305x170 (Output Slotted, WxLxH)		Max. 105x305x170 (Output Slotted, WxLxH) & Steak Magazine	
	Machine Time	sec	Max. 40		Max. 22	
Molding Parameter	Mold Temperature	°C	Ref. 175 ± 3			
	Clamp Tonnage	ton	Max. 10 (Servo Motor Driven)		Max. 175 (per Chase)	
	Transfer Tonnage	ton	Max. 10		Max. 5	
	Compound Curing Time	sec	Ref. 60 ~ 120		Ref. 45 ~ 120	
	Others		Pre Heating (sec)	Ref. 6 ~ 20	Transfer Speed (mm/sec)	10.0 (Max)
System Reliability	MTBA	hours	2			
	MTBF		168			
	MTTA	minutes	Max. 3			
	MTTR		Max. 30			
Molding Compound			Powder	Capable	Diameter (mm)	Φ13 ~ Φ20
			Liquid	N/A	Size (mm)	Max. Φ20 (H:28)
			EMC Weight Control	± 0.1 gram (Target)	EMC Ratio (%)	90